



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Shibaek Nam; Oseob Jeon; and Chulho Heo  
Assignee: Fairchild Semiconductor Corporation  
Title: Semiconductor Device Having Multi-Chip Package Structure  
Application No.: 10-038,714 Filing Date: January 2, 2002  
Examiner: Pershelle L. Greene Group Art Unit: 2826  
Docket No.: M-11590 US Confirmation No.: 8922

San Francisco, California  
February 19, 2003

COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

**NOTICE OF CHANGE OF ADDRESS**

Dear Sir:

Please direct all correspondence in the above-identified application and with respect to any patent that issues on this application to the undersigned at this address:

Philip W. Woo  
c/o SIDLEY AUSTIN BROWN & WOOD LLP  
555 CALIFORNIA STREET  
SUITE 5000  
SAN FRANCISCO, CA 94104-1715  
TEL. (415) 772-1200  
FAX (415) 397-4621

Certificate of Mailing

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.

Respectfully submitted,

Philip W. Woo  
Attorney of Record